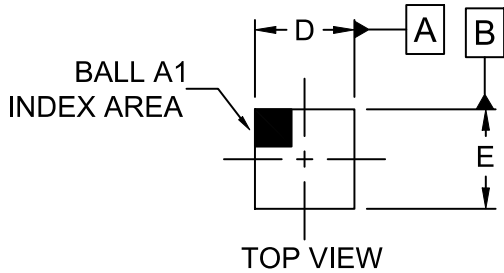


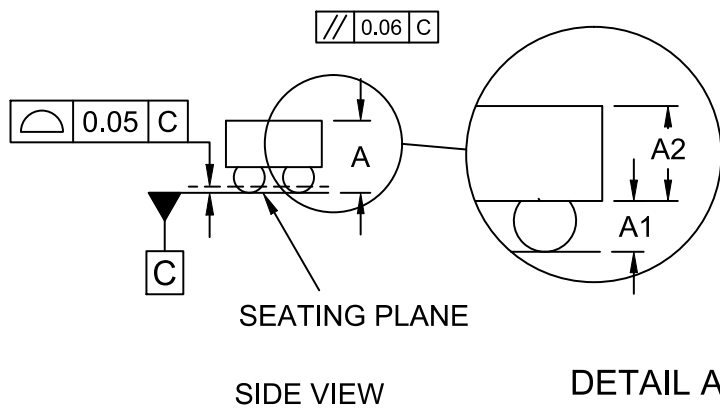
WLCSP4, 0.815x0.815x0.457
CASE 567VT
ISSUE O

DATE 31 JAN 2018

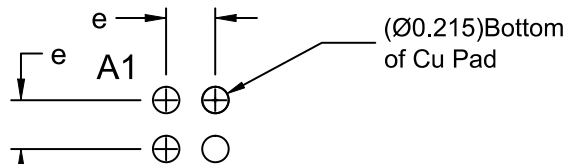
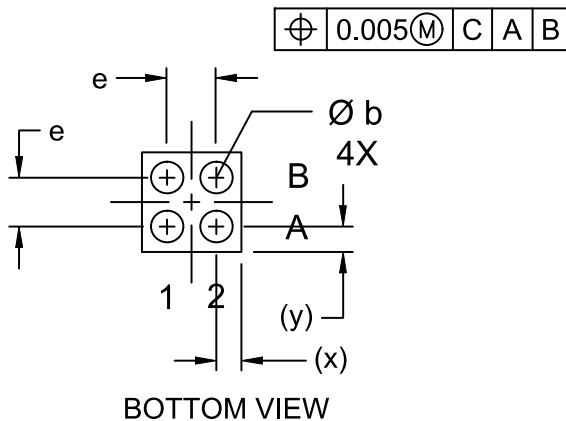


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS




| DIM | MILLIMETERS | | |
|-----|-------------|--------|--------|
| | MIN. | NOM. | MAX. |
| A | 0.419 | 0.457 | 0.495 |
| A1 | 0.183 | 0.203 | 0.223 |
| A2 | 0.236 | 0.254 | 0.272 |
| b | 0.240 | 0.260 | 0.280 |
| D | 0.785 | 0.815 | 0.845 |
| E | 0.785 | 0.815 | 0.845 |
| e | 0.40 BSC | | |
| x | 0.1925 | 0.2075 | 0.2225 |
| y | 0.1925 | 0.2075 | 0.2225 |



(NSMD PAD TYPE)

| | | |
|-------------------------|----------------------------------|--|
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| DESCRIPTION: | WLCSP4, 0.815x0.815x0.457 | PAGE 1 OF 1 |

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